



## **1GLOBAL FOR THINGS SIM DATASHEET**

### Smart SIM for Seamless IoT Connectivity

1GLOBAL's secure IoT SIM not only connects your devices securely to our global network, each one is shipped with eSIM technology as standard.

#### **Highlights:**

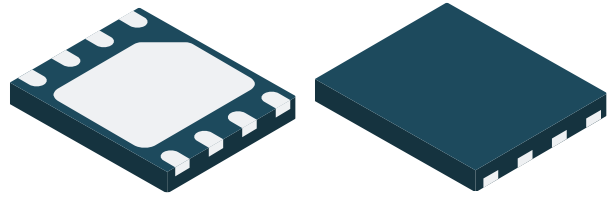
- Simple out of the box connectivity experience;
- Single contract for multi-country deployments with our global network and IoT platform;
- Simplify SIM logistics with a single SKU across the world;
- Better service management control with local operations and direct agreements with Tier 1 providers;
- Faster time-to-market with proven experience to deploy mobile services in new markets;
- Reliable global service focused on quality and fast delivery.

#### **Technical Features:**

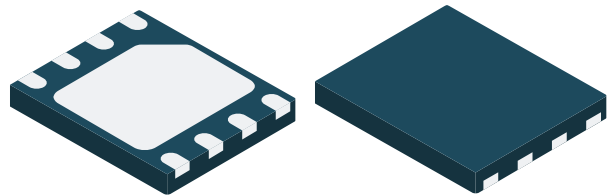
- Remote SIM provisioning compliant with GSMA M2M and SIMalliance specifications;
- Inbuilt bootstrap connectivity profile;
- Up to 10 operator profiles on a single eSIM;
- Compliant with 2G / 3G / 4G (LTE) / CDMA / NB-IoT / CAT-M networks;
- Network access applications supported: SIM / USIM / ISIM / CSIM;
- Power saving features;
- Secure element access control (ARF / PKCS#15);
- OTA capability over SMS, CAT-TP & HTTPS (including DNS);
- Multi-interfaces able to combine eSIM + eSE.

## SIM Types

SKU	SIM-S-I03-MFF2-2
Format	MFF2
Dimensions	5x6x1.27mm
Chip Manufacturer	ST Microelectronics
Chip Reference	ST33G1M2
SIM Vendor	ST Microelectronics
Low Power Support	Yes



SKU	SIM-S-I03-MFF2-2-LP
Format	MFF2
Dimensions	5x6x1.27mm
Chip Manufacturer	ST Microelectronics
Chip Reference	ST33G1M2
SIM Vendor	ST Microelectronics
Low Power Support	Yes

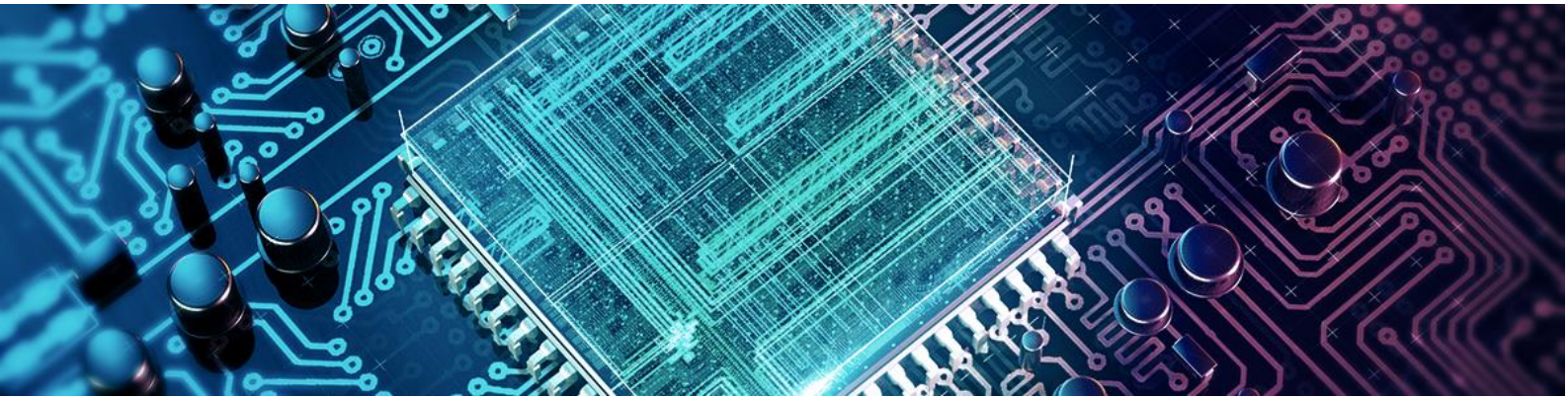


SKU	SIM-S-I03-TRI-2
Format	2FF/3FF/4FF
Dimensions	4FF: 12.3x8.8x.67mm
Chip Manufacturer	ST Microelectronics
Chip Reference	ST33G1M2
SIM Vendor	ST Microelectronics
Low Power Support	Yes



SKU	SIM-S-I03-TRI-2-LP
Format	2FF/3FF/4FF
Dimensions	4FF: 12.3x8.8x.67mm
Chip Manufacturer	ST Microelectronics
Chip Reference	ST33G1M2
SIM Vendor	ST Microelectronics
Low Power Support	Yes





## Hardware Features

### Chip Type

Supplier	ST Microelectronics
Chip Codes	ST33G1M2M
Technology	80 nm
CPU	ARM 32-bit RISC SC300

### Qualification

Common Criteria EAL5+  
Industrial Qualification (JEDEC JESD47)

### Electrical Characteristics

Supply voltage (All formats):  
Class A (5 V), Class B (3 V), Class C (1.8 V)

### Operational Temperature Characteristics

Temperature Range 4FF	-25° to +85°
Extended Range MFF2	-40° to +105°

### Supported Clock Division Factors

F/D = 372 (F=372, D=1)	Yes
F/D = 64 (F=512, D=8)	Yes
F/D = 32 (F=512, D=16)	Yes
F/D = 16 (F=512, D=32)	Yes
F/D = 8 (F=512, D=64)	Yes

### Memory Sizes

Total Flash size	1280K
Flash available to customer	380K / 512K (Ext)
RAM Total / For applets	30K / 7K

### NVRAM characteristics

Endurance cycles (min) @25°	100K / 500K (Ext)
Data retention (min) @25°	10 Y / 25 Y (Ext)
Page/Sector erase time	3ms/6ms
Page write time	2.5ms

### Cryptographic Features and Accelerators

Crypto-coprocessor	Yes
3DES engine	Yes
AES engine	Yes
True RNG	Yes
CRC	Yes
CPA /DPA Countermeasures	Yes

### Form Factors

3 in 1 Plug-In SIM (2FF, 3FF and 4FF)	Yes
DFN8 (MFF2)	Yes
WLCSP	Yes



## Software Features

### Platform

UICC	Release 12
Java Card	3.0.4
Global Platform Certified	2.2 (Amd. A,B,C,D,E)
SIMAlliance IPP	2.1
GMSA RSP SGP.02 M2M	3.2
Power Saving Features (PSM, eDRX)	ETSI R13

### Supported Applications

USIM	Release 12
ISIM	Release 12
EAP	Release 12

### Multiplication Features

Single SIM/ multiple USIMs / ISIMs	Yes
Number of Logical Channels	4

### Supported Java Card APIs

UICC API	Release 12
USIM API	Release 12
ISIM API	Release 12
Global Platform API	2.2.1

### Supported Protocols

T=0	Yes
T=1	Yes

### Memory Management

Journaling File System	Yes (Option)
Dynamic Memory Management	Yes

### Administration

Administrative Commands	Release 12
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### Remote Management

Remote File Management	Release 12
Remote Applet Management	Release 12
SMS Concatenation Size	configurable
BIP	Release 12
CAT_TP	Release 12
HTTPS Remote Management	Yes

### Authentication Algorithms

2G COMP128-1,2,3	Yes
2G GSM-MILENAGE	Yes
3G MILENAGE	Yes
GBA Support	Yes
TUAK	Yes
ECC (NIST P-256, brainpoolIP256r1)	Yes
RSA (up to 2048 bits)	Yes

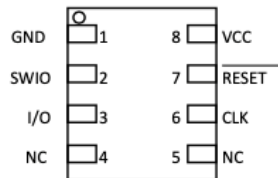




## MFF2 Pin Out

This package is compatible with the MFF2 package defined by ETSI 102 671 release 12.

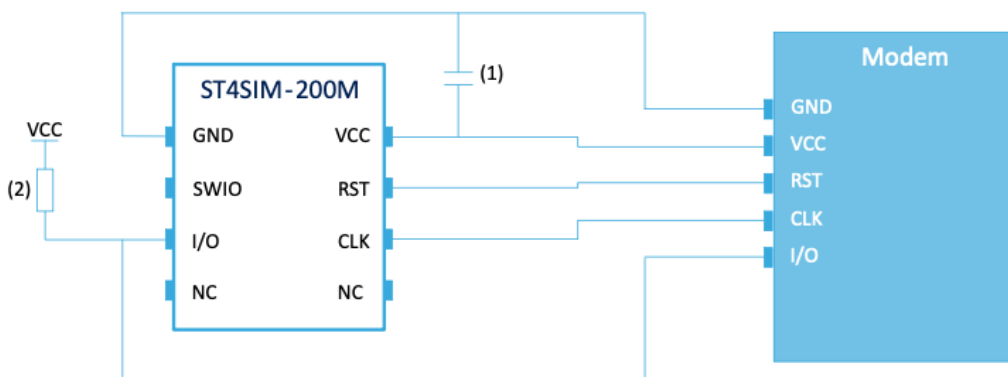
**Figure 1. VFDFPN8 pinout (top view)**



**Table 1. Pin descriptions**

Name	Description	Pin state
GND	Ground supply	-
SWIO	Not used	Input pull-up
RESET	External reset	Input pull-down
I/O	Input/output	Pull-down then pull-up after card activation
CLK	External clock	Pull-down
VCC	Power supply	-
NC	Not connected internally	-

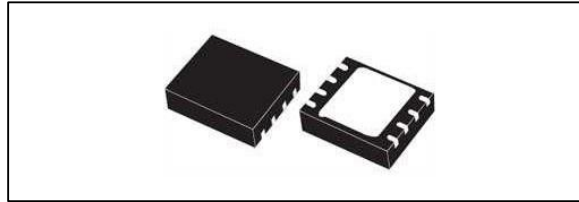
**Figure 2. ST4SIM-200M PCB integration recommendations**



## Packaging information

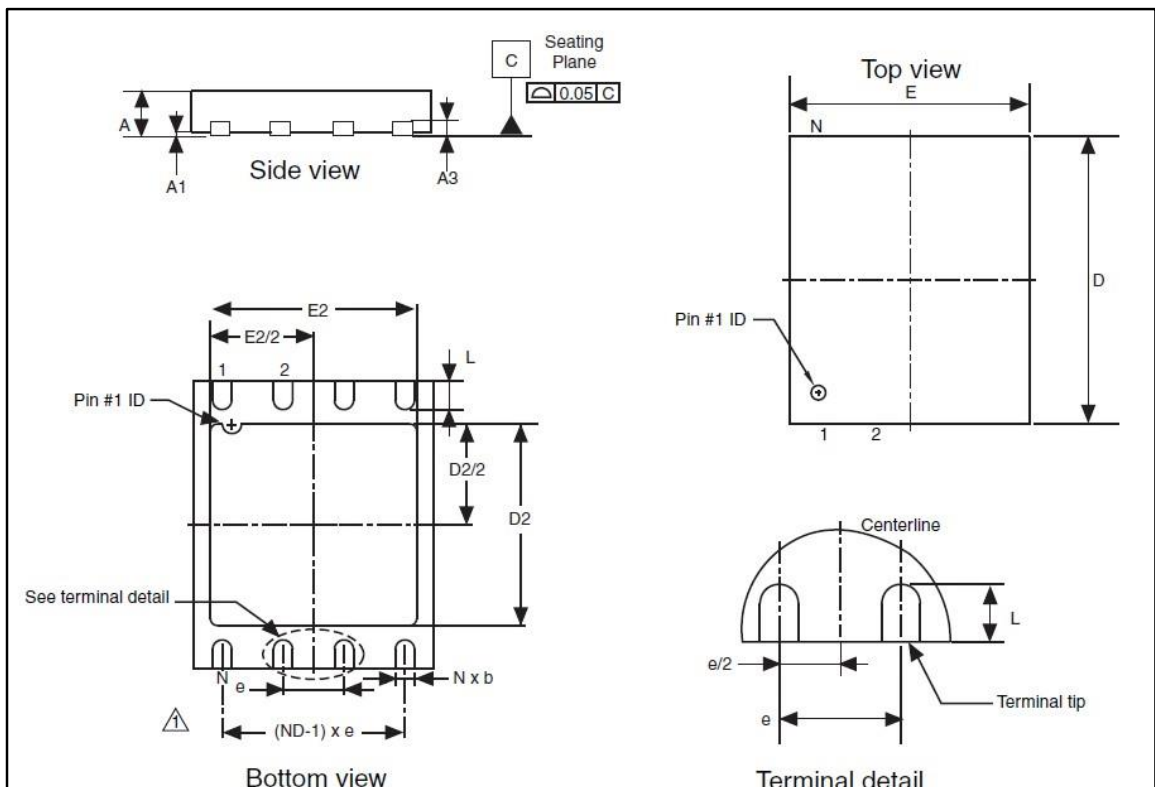
This section of the document defines the packaging requirements for M2M personalized products, based on the DFN8/MFF2 5 × 6 mm package.

Package silhouette



## Package mechanical data

DFN8 5 × 6 mm (0.9 mm thickness) package outline



5 × 6 mm, 0.9 mm thickness package mechanical data

Symbol	millimeters			inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.800	0.900	1.000	0.0315	0.0354	0.0394
A1	0.000	0.020	0.050	0.0000	0.0008	0.0020
A3		0.200			0.0079	
b	0.350	0.400	0.480	0.0138	0.0157	0.0189
D	5.900	6.000	6.100	0.2322	0.2362	0.2401
D2	3.300	3.400	3.500	0.1299	0.1339	0.1378
E	4.900	5.000	5.100	0.1929	0.1969	0.2007
E2	4.100	4.200	4.300	0.1614	0.1654	0.1693
e		1.270			0.0500	
L	0.500	0.600	0.750	0.0197	0.0236	0.0295

1. Values in inches are converted from mm and rounded to 4 decimal digits.

- Note:**
- 1 'N' is the total number of terminals.
  - 2 'ND' refer to the number of terminals on side D.
  - 3 Max. package warpage is 0.05 mm.
  - 4 Max. allowable burrs is 0.076 mm in all directions.
  - 5 Pin #ID on top will be laser marked.

## Tape and reel packaging

Surface-mount packages can be supplied with Tape and Reel packing. Typical reels diameter 13" (4000 devices).

Reels are in plastic, either antistatic or conductive, with a black conductive cavity tape.

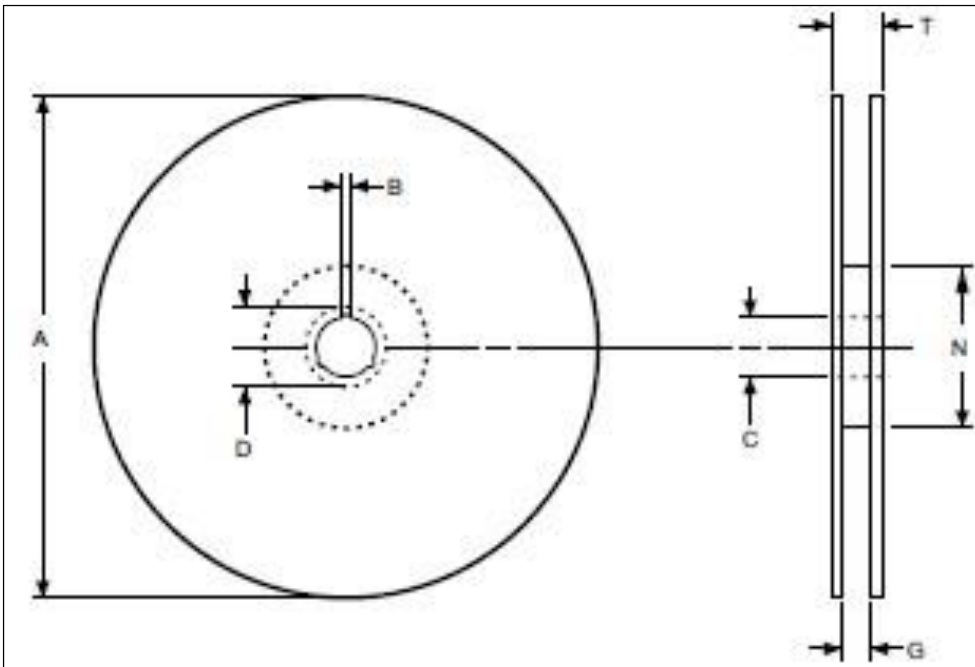
The cover tape is transparent antistatic or conductive.

The STMicroelectronics Tape & Reel specifications are compliant to the EIA 481-A standard specification.

### Packages on tape and reel

Package	Description	Tape width	Tape pitch	Reel diameter	Quantity per reel
DFN 5 x 6	Flat package no. lead 5 x 6 mm	14 mm	8mm	13 in.	4000

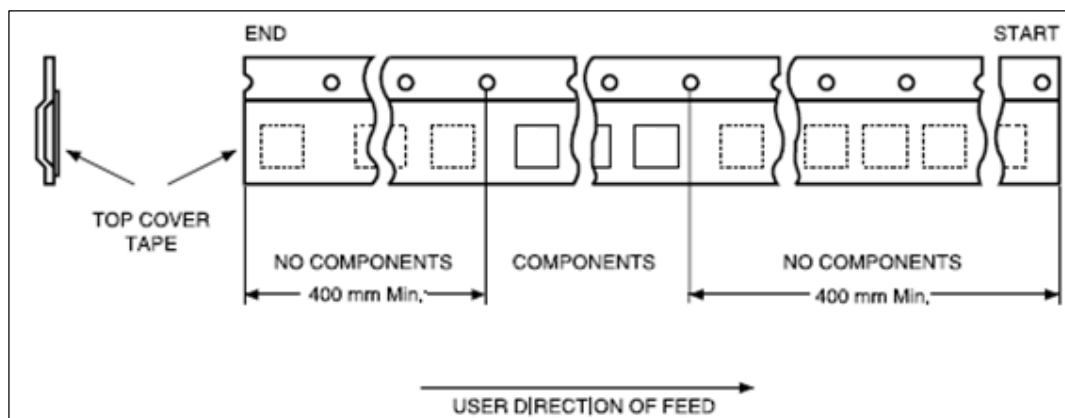
**Reel diagram**



**Reel dimensions**

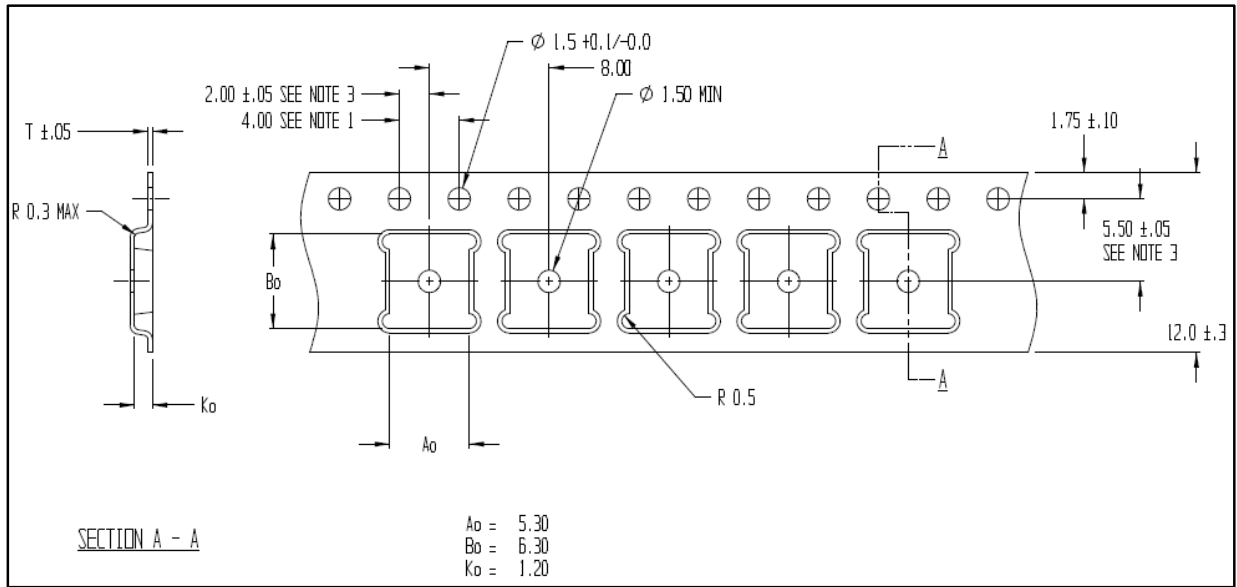
Reel size	Tape size	A max	B min	C	D min	G max	N min	T max	Unit
13"	12 mm	330	1,5	13 ±0,25	20,2	12,6	100	18,4	mm

**Leader and trailer**

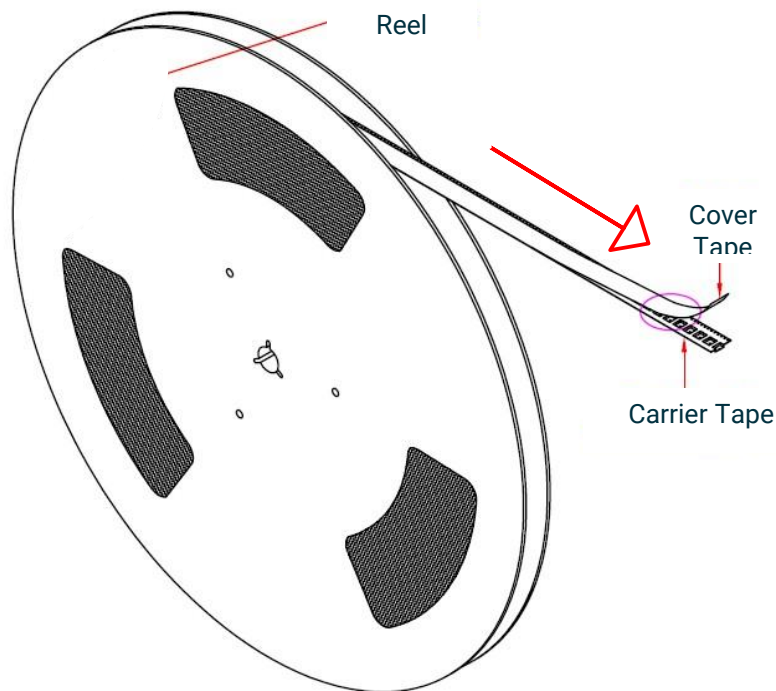


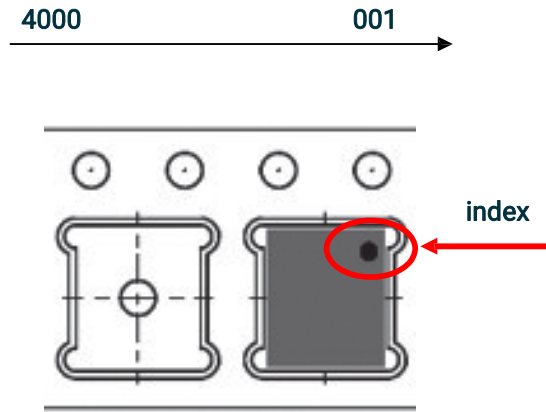


**Embossed carrier tape**



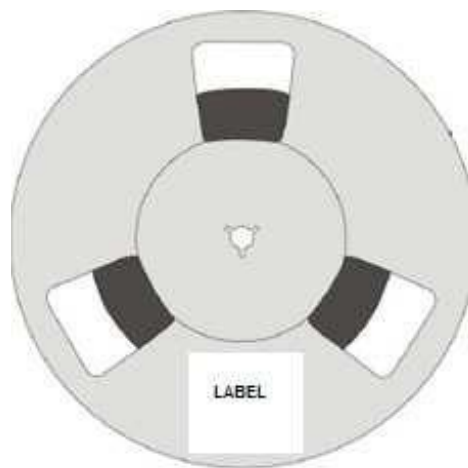
**Component orientation**





**Identification reel**

A dedicated label with logistic information shall be placed onto the reel.



**Dry packaging of reel in moisture barrier bag**

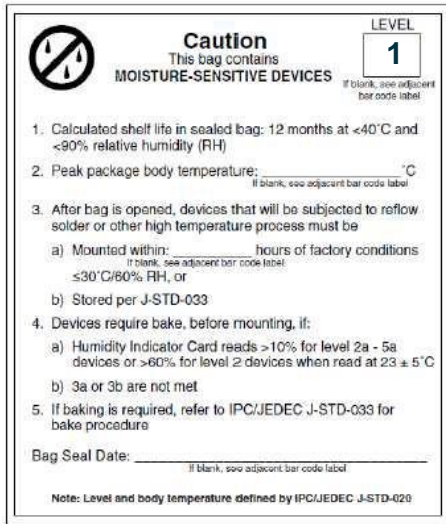
The reel is packed in a moisture barrier bag.

In the bag is inserted a humidity indicator card and desiccant bag.



On the moisture barrier bag are stuck the labels:

- 1) Moisture sensitive caution label
- 2) A logistic label containing reel information (as per customer request)



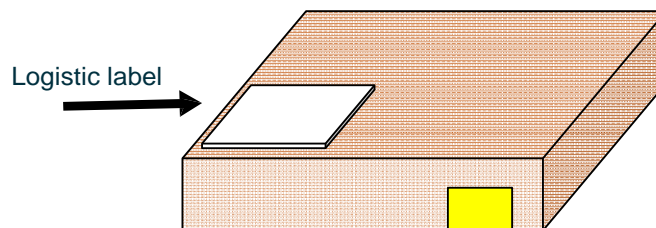
This package is qualified in compliance with JEDEC J-STD-020D and MSL 1 specifications.

**Shipping box and packaging**

The reel, shrunken inside the moisture barrier bag, shall be shipped in a dedicated shipping box. The packed reel is put in a cardboard box of dimensions 365x350x45 mm.

On the top is stuck a logistic label containing reel information (as per customer request)

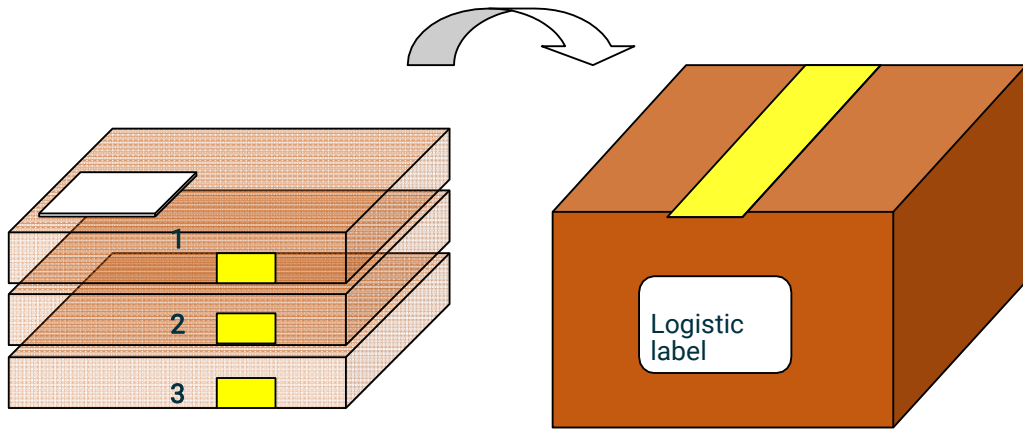
The box shall be sealed with a security tape.



Packaging in the over box: “three shipping boxes = 12.000 pcs.” - results in outer box max external dimensions:

- X: 395 mm
- Y: 375 mm

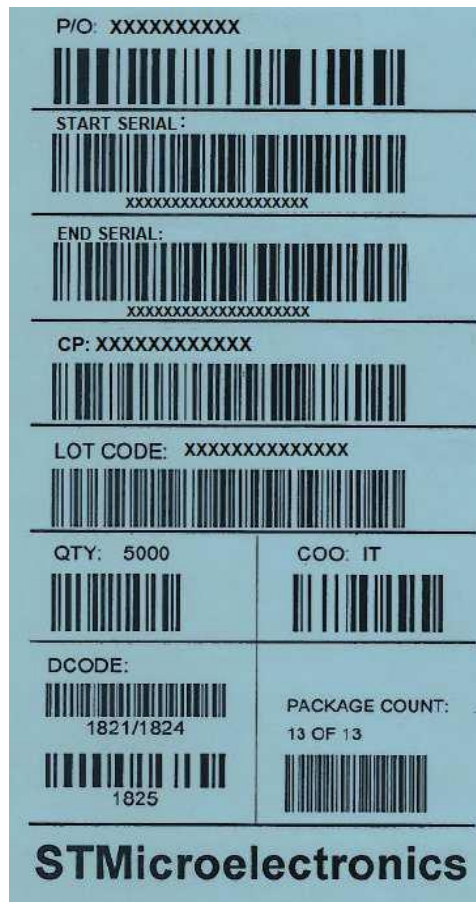
• H: 170 mm



A dedicated outer box label with logistic information shall be placed centered to the front side of the outer box.  
 The outer boxes shall be sealed with a security tape.

**Standard Label**

The following label will be applied on the reel, moisture barrier bag, cardboard box and if necessary, also on the overbox:

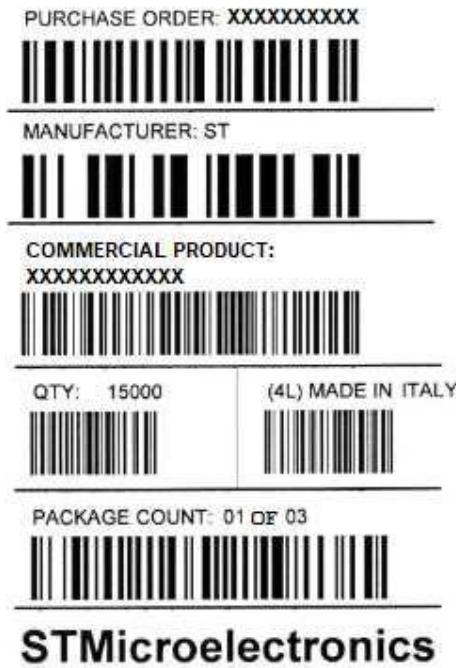
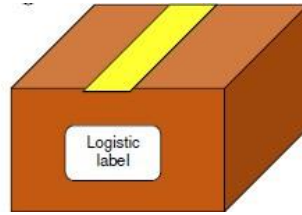


Date	Type	Print Format	Digit	Min Barcode degree
Purchase Order P/O	V	Numeric	10	NA
Purchase Order P/O	V	BarCode 128	10	D
Start Serial	V	Numeric	20	NA
Start Serial	V	BarCode 128	20	D
End Serial	V	Numeric	20	NA
End Serial	V	BarCode 128	20	D
CP Commercial Product	F	XXXXXXXXXXXX	NA	NA
CP Commercial Product	F	BarCode 128 XXXXXXXXXXXX	NA	D
Lot Code	V	XXXXXXXXXXXX	NA	NA
Lot Code	V	BarCode 128 XXXXXXXXXXXX	NA	D
QTY	V	Numeric	4	NA
QTY	V	BarCode 128	4	D
COO	F	IT	2	NA
COO	F	BarCode 128	2	D
Dcode	V	YYWW	4	NA
Dcode	V	YYWW BarCode 128	4	D
Package Count	V	Reel identification in relation to the total of the reel belonging to the order	6	NA
PAckage Count	V	BarCode 128  Reel identification in relation to the total of the reel belonging to the order	6	D



Note: V = variable data; F = fixed data

**OVERBOX LABELS (the overbox can include max 3 box):**



Date	Type	Print Format	Digit	Min Barcode degree
Purchase Order P/O	V	Numeric	10	NA
Purchase Order P/O	V	BarCode 128	10	D
Manufacturer	F	ST	2	NA
Manufacturer	F	ST	2	NA
Commercial Product	F	XXXXXXXXXXXX	NA	NA

Commercial Product	F	BarCode 128 XXXXXXXXXXXX	NA	D
QTY	V	Numeric	4-5	NA
QTY	V	BarCode 128	4-5	D
4L) MADE IN ITALY	F	FIXED STRING (4L) MADE IN ITALY	18	NA
ITALY	F	BarCode 128	13	D
Package Count	V	<p>"0X" OF "0Y" where 0X indicates the box number, while 0Y indicates the total number of boxes.</p> <p>For example, if the production is 35,000 chips, there will be 3 boxes that will report respectively: 01 OF 03, 02 OF 03, 03, 0F, 03</p>	6	NA
Package Count	V	<p>BarCode 128 "0X" OF "0Y" where 0X indicates the box number, while 0Y indicates the total number of boxes</p>	6	D